

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claims 1-14 (canceled).

Claim 15 (currently amended): A composite ceramic substrate comprising:
a ceramic substrate including a surface-mounted component mounted thereon;
at least one wiring pattern disposed in the ceramic substrate;
~~at least one a plurality of~~ external terminal electrodes connecting the at least one wiring pattern to a surface electrode of a motherboard;

~~at least one a plurality of~~ convex leg portions made of resin and arranged on the ceramic substrate such that a first end surface of each of the at least one plurality of convex leg portions supports a respective one of the at least one plurality of external terminal electrodes and a second end surface of each of the at least one plurality of convex leg portions opposite to the first end surface is in direct contact with and directly connected to the ceramic substrate; and

a via-hole conductor provided in each of the at least one plurality of convex leg portions and connecting the respective one of the at least one plurality of external terminal electrodes to the at least one wiring pattern; wherein

the plurality of convex leg portions are arranged so as to be spaced apart from one another.

Claim 16 (currently amended): The composite ceramic substrate according to claim 15, wherein the surface-mounted component is mounted on at least one of a first main surface and a second main surface of the ceramic substrate and the plurality of convex leg portions are ~~is~~ disposed on the second main surface of the ceramic substrate.

Claim 17 (currently amended): The composite ceramic substrate according to claim 16, wherein the plurality of convex leg portions ~~are~~^{is} disposed at a periphery of the second main surface of the ceramic substrate.

Claim 18 (canceled).

Claim 19 (withdrawn-currently amended): The composite ceramic substrate according to claim ~~48~~¹⁵, wherein none of the plurality of external terminal electrodes are disposed at corners of the second main surface of the ceramic substrate.

Claim 20 (withdrawn): The composite ceramic substrate according to claim 19, wherein the corners are disposed at a height that is lower than a height at which the external terminal electrodes are disposed.

Claim 21 (withdrawn-currently amended): The composite ceramic substrate according to claim 16, wherein ~~at least one convex leg portions include a plurality of convex leg portions, and~~ the surface-mounted component is mounted between the plurality of convex leg portions on the second main surface.

Claim 22 (withdrawn): The composite ceramic substrate according to claim 21, wherein the surface-mounted component is coated with resin that is the same as the resin from which the plurality of convex leg portions are made.

Claim 23 (withdrawn): The composite ceramic substrate according to claim 22, wherein a round portion is provided between the plurality of convex leg portions and the resin coating the surface-mounted component.

Claim 24 (withdrawn-currently amended): The composite ceramic substrate

according to claim 22, wherein ~~the~~ a surface of the resin coating the surface-mounted component includes a slit.

Claim 25 (withdrawn-currently amended): The composite ceramic substrate according to claim 15, wherein an edge of each of the plurality of convex leg portions has a rounded shape.

Claim 26 (previously presented): The composite ceramic substrate according to claim 15, wherein the via-hole conductor is made of a flexible conductive resin.

Claim 27 (previously presented): The composite ceramic substrate according to claim 15, wherein the ceramic substrate is a multilayer ceramic substrate including a plurality of laminated low temperature co-fired ceramic layers.

Claim 28 (previously presented): The composite ceramic substrate according to claim 15, wherein the surface-mounted component includes an array of external terminal electrodes.